# Hybrid IGBT, 50 A, 650 V

## AFGHL50T65SQDC

Using the novel field stop 4<sup>th</sup> generation IGBT technology and the 1.5<sup>th</sup> generation SiC Schottky Diode technology, AFGHL50T65SQDC offers the optimum performance with both low conduction and switching losses for high efficiency operations in various applications, especially totem pole bridgeless PFC and Inverter.

#### **Features**

- AEC-Q101 Qualified
- Maximum Junction Temperature :  $T_J = 175$ °C
- Positive Temperature Co-efficient for Easy Parallel Operating
- High Current Capability
- Low Saturation Voltage:  $V_{CE(Sat)} = 1.6 \text{ V (Typ.)} @I_C = 50 \text{ A}$
- Fast Switching
- Tighten Parameter Distribution
- No Reverse Recovery/No Forward Recovery

## **Typical Applications**

- Automotive
- On & Off Board Chargers
- DC-DC Converters
- PFC
- Industrial Inverter

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector to Emitter Voltage	V <sub>CES</sub>	650	V
Gate to Emitter Voltage Transient Gate to Emitter Voltage	V <sub>GES</sub>	±20 ±30	V
Collector Current $@T_C = 25^{\circ}C$ $@T_C = 100^{\circ}C$	Ic	100 50	Α
Pulsed Collector Current (Note 1)	$I_{LM}$	200	Α
Pulsed Collector Current (Note 2)	I <sub>CM</sub>	200	Α
Diode Forward Current @T <sub>C</sub> = 25°C @T <sub>C</sub> = 100°C	I <sub>F</sub>	40 20	Α
Pulsed Diode Maximum Forward Current	I <sub>FM</sub>	200	Α
Maximum Power Dissipation @T <sub>C</sub> = 25°C @T <sub>C</sub> = 100°C	P <sub>D</sub>	238 119	W
Operating Junction / Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	±55 to +175	°C
Maximum Lead Temp. for Soldering Purposes, 1/8" from case for 5 seconds	TL	300	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

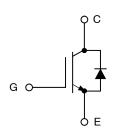
- 1.  $V_{CC}$  = 400 V,  $V_{GE}$  = 15 V,  $I_{C}$  = 200 A,  $R_{G}$  = 26  $\Omega$ , Inductive Load, 100% Tested.
- 2. Repetitive Rating: pulse width limited by max. Junction temperature.

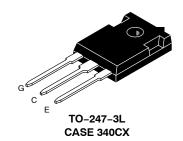


ON Semiconductor®

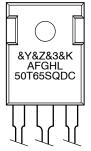
www.onsemi.com

50 A, 650 V V<sub>CESat</sub> = 1.6 V (Typ.)





#### **MARKING DIAGRAM**



&Y = ON Semiconductor Logo &Z = Assembly Plant Code &3 = 3-Digit Data Code

&K = 2-Digit Lot Traceability Code AFGHL50T65SQDC = Specific Device Code

## ORDERING INFORMATION

Device	Package	Shipping
AFGHL50T65SQDC	TO-247-3L	30 Units / Rail

#### THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal resistance junction-to-case, for IGBT	$R_{ heta JC}$	0.63	°C/W
Thermal resistance junction-to-case, for Diode	$R_{ heta JC}$	1.55	°C/W
Thermal resistance junction-to-ambient	$R_{ heta JA}$	40	°C/W

## **ELECTRICAL CHARACTERISTICS** (T<sub>.1</sub> = 25°C unless otherwise noted)

Parameter	Test Conditions	Symbol	Min.	Тур.	Max.	Unit
OFF CHARACTERISTICS				•	•	
Collector-emitter breakdown voltage, gate-emitter short-circuited	V <sub>GE</sub> = 0 V, I <sub>C</sub> = 1 mA	BV <sub>CES</sub>	650	-	_	V
Temperature Coefficient of Breakdown Voltage	V <sub>GE</sub> = 0 V, I <sub>C</sub> = 1 mA	$\frac{\Delta BV_{CES}}{\Delta T_{J}}$	-	0.6	-	V/°C
Collector-emitter cut-off current, gate-emitter short-circuited	V <sub>GE</sub> = 0 V, V <sub>CE</sub> = 650 V	I <sub>CES</sub>	-	-	250	μΑ
Gate leakage current, collector-emitter short-circuited	V <sub>GE</sub> = 20 V, V <sub>CE</sub> = 0 V	I <sub>GES</sub>	-	-	±400	nA
ON CHARACTERISTICS						-
Gate-emitter threshold voltage	$V_{GE} = V_{CE}$ , $I_C = 50 \text{ mA}$	$V_{GE(th)}$	3.4	4.9	6.4	V
Collector-emitter saturation voltage	$V_{GE}$ = 15 V, $I_{C}$ = 50 A $V_{GE}$ = 15 V, $I_{C}$ = 50 A, $T_{J}$ = 175°C	V <sub>CE(sat)</sub>	-	1.6 1.9	2.1 -	V
DYNAMIC CHARACTERISTICS					•	
Input capacitance	V <sub>CE</sub> = 30 V,	C <sub>ies</sub>	-	3098	_	pF
Output capacitance	V <sub>GE</sub> = 0 V, f = 1 MHz	C <sub>oes</sub>	-	265	-	
Reverse transfer capacitance		C <sub>res</sub>	-	9	-	
Gate charge total	V <sub>CE</sub> = 400 V,	$Q_g$	-	94	_	nC
Gate to emitter charge	I <sub>C</sub> = 50 V, V <sub>GE</sub> = 15 V	$Q_ge$	-	18	_	
Gate to collector charge		$Q_{gc}$	-	23	_	
SWITCHING CHARACTERISTICS						
Turn-on delay time	T <sub>J</sub> = 25°C	t <sub>d(on)</sub>	-	17.6	_	ns
Rise time	VCC = 400 V, IC = 12.5 A	t <sub>r</sub>	-	6.4	-	
Turn-off delay time	$R_G = 4.7 \Omega$ $V_{GE} = 15 V$	t <sub>d(off)</sub>	-	94.4	-	
Fall time	Inductive Load	t <sub>f</sub>	=	14.4	-	
Turn-on switching loss		E <sub>on</sub>	=	131	-	μJ
Turn-off switching loss		E <sub>off</sub>	=	96	-	
Total switching loss		E <sub>ts</sub>	=	227	_	
Turn-on delay time	T <sub>J</sub> = 25°C	t <sub>d(on)</sub>	-	19.2	-	ns
Rise time	$VCC = 400 \text{ V},$ $IC = 25 \text{ A}$ $R_G = 4.7 \Omega$ $V_{GE} = 15 \text{ V}$	t <sub>r</sub>	-	11.2	-	
Turn-off delay time		td <sub>(off)</sub>	-	89.6	-	
Fall time	Inductive Load	t <sub>f</sub>	-	6.4	-	
Turn-on switching loss		Eon	-	311	-	μЈ
Turn-off switching loss		Eoff	-	141	-	
Total switching loss	1	Ets	_	452	-	

## **ELECTRICAL CHARACTERISTICS** ( $T_J = 25^{\circ}C$ unless otherwise noted)

Parameter	Test Conditions	Symbol	Min.	Тур.	Max.	Unit
SWITCHING CHARACTERISTICS	•	•		•	•	•
Turn-on delay time	T <sub>J</sub> = 175°C	t <sub>d(on)</sub>	_	16	_	ns
Rise time	VCC = 400 V, IC = 12.5 A	t <sub>r</sub>	-	8	-	1
Turn-off delay time	$R_G = 4.7 \Omega$ $V_{GE} = 15 V$	t <sub>d(off)</sub>	-	107.2	-	1
Fall time	Inductive Load	t <sub>f</sub>	-	53.6	-	1
Turn-on switching loss		E <sub>on</sub>	_	157	_	μJ
Turn-off switching loss		E <sub>off</sub>	_	193	_	1
Total switching loss		E <sub>ts</sub>	_	350	_	1
Turn-on delay time	T <sub>J</sub> = 175°C	t <sub>d(on)</sub>	_	17.6	_	ns
Rise time	VCC = 400 V, IC = 25 A	t <sub>r</sub>	_	14.4	_	1
Turn-off delay time	$R_G = 4.7 \Omega$ $V_{GE} = 15 V$	t <sub>d(off)</sub>	_	99.2	_	1
Fall time	Inductive Load	t <sub>f</sub>	_	9.6	_	1
Turn-on switching loss		E <sub>on</sub>	_	350	_	μJ
Turn-off switching loss		E <sub>off</sub>	-	328	-	1
Total switching loss		E <sub>ts</sub>	-	678	-	1
DIODE CHARACTERISTICS						
Forward voltage	I <sub>F</sub> = 20 A I <sub>F</sub> = 20 A, T <sub>J</sub> = 175°C	V <sub>F</sub>	=	1.45 1.83	1.75 -	V
Total Capacitance	V <sub>R</sub> = 400 V, f = 1 MHz	С	-	103	-	pF
	V <sub>R</sub> = 600 V, f = 1 MHz	1	-	99	_	1

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

#### **TYPICAL CHARACTERISTICS**

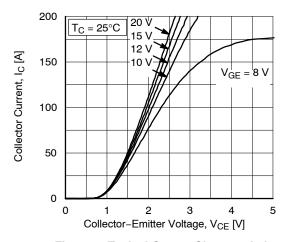


Figure 1. Typical Output Characteristics  $(T_C = 25^{\circ}C)$ 

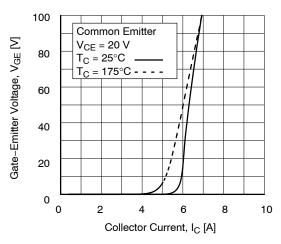


Figure 3. Transfer Characteristics

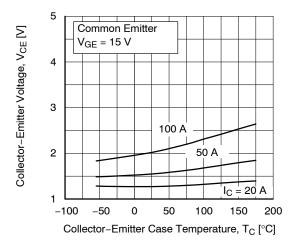


Figure 5. Saturation Voltage vs. Case Temperature at Variant Current Level

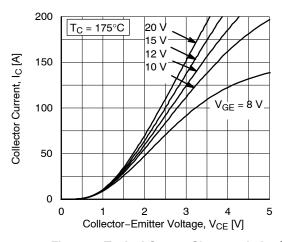


Figure 2. Typical Output Characteristics "
(T<sub>C</sub> = 175°C)

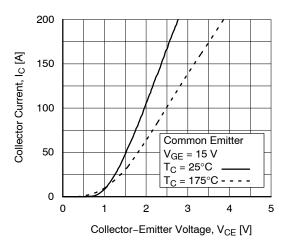


Figure 4. Typical Saturation Voltage Characteristics

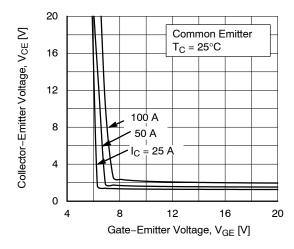


Figure 6. Saturation Voltage vs.  $V_{GE}$  ( $T_C = 25^{\circ}C$ )

#### TYPICAL CHARACTERISTICS (continued)

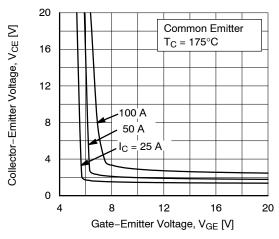


Figure 7. Saturation Voltage vs. V<sub>GE</sub> (T<sub>C</sub> = 175°C)

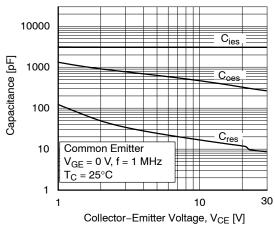


Figure 8. Capacitance Characteristics

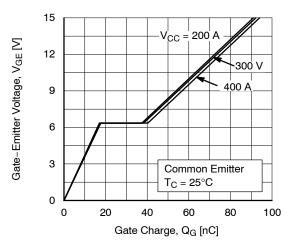


Figure 9. Gate Charge Characteristics (T<sub>C</sub> = 25°C)

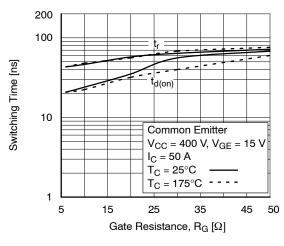


Figure 10. Turn-on Characteristics vs. Gate Resistance

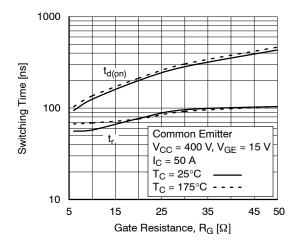


Figure 11. Turn-Off Characteristics vs. Resistance

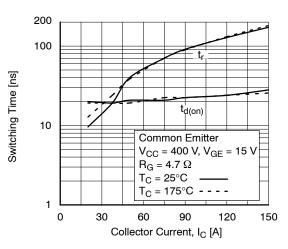


Figure 12. Turn-On Characteristics vs. Collector Current

#### TYPICAL CHARACTERISTICS (continued)

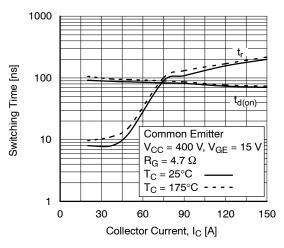


Figure 13. Turn-Off Characteristics vs. Collector Current

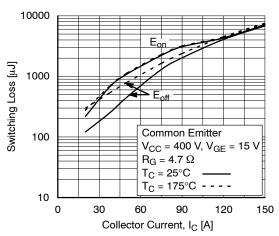


Figure 15. Switching Loss vs. Collector Current

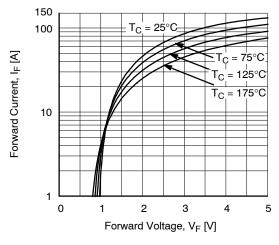


Figure 17. (Diode) Forward Characteristics vs. (Normal I–V)

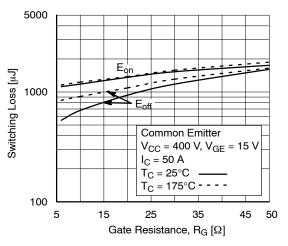


Figure 14. Switching Loss vs. Gate Resistance

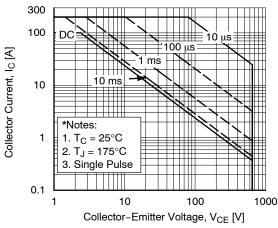


Figure 16. SOA Characteristics (FBSOA)

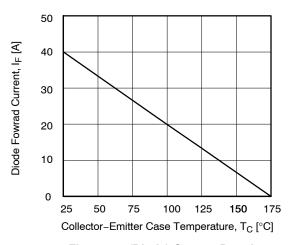


Figure 18. (Diode) Current Derating

## TYPICAL CHARACTERISTICS (continued)

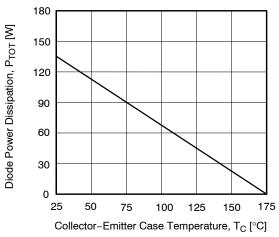


Figure 19. (Diode) Power Derating

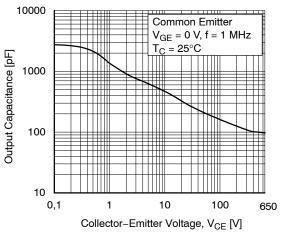


Figure 20. (Diode) Output Capacitance (Coes) vs. Reverse Voltage

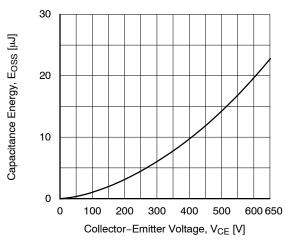


Figure 21. Output Capacitance Stored Energy

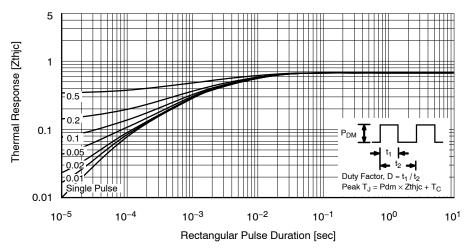


Figure 22. Transient Thermal Impedance of IGBT

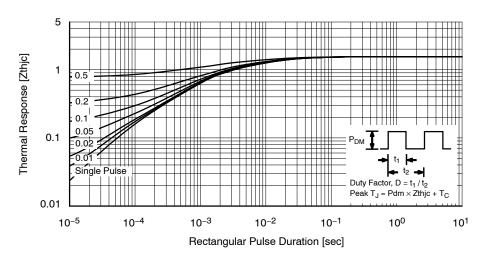
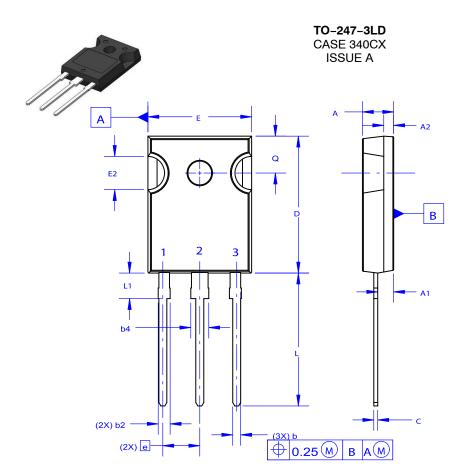


Figure 23. Transient Thermal Impedance of Diode

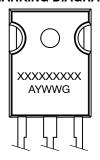
**DATE 06 JUL 2020** 



NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
- D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.

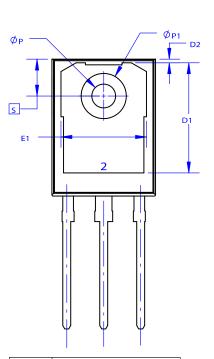
# GENERIC MARKING DIAGRAM\*



XXXXX = Specific Device Code A = Assembly Location

Y = Year WW = Work Week G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " •", may or may not be present. Some products may not follow the Generic Marking.



DIM	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	4.58	4.70	4.82	
<b>A</b> 1	2.20	2.40	2.60	
A2	1.40	1.50	1.60	
D	20.32	20.57	20.82	
E	15.37	15.62	15.87	
E2	4.96	5.08	5.20	
е	~	5.56	~	
L	19.75	20.00	20.25	
L1	3.69	3.81	3.93	
ØΡ	3.51	3.58	3.65	
Q	5.34	5.46	5.58	
S	5.34	5.46	5.58	
b	1.17	1.26	1.35	
b2	1.53	1.65	1.77	
b4	2.42	2.54	2.66	
С	0.51	0.61	0.71	
D1	13.08	~	~	
D2	0.51	0.93	1.35	
E1	12.81	~	~	
ØP1	6.60	6.80	7.00	

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